



## Final Product Change Notification

201901014F01

**Issue Date:** 09-Feb-2019

**Effective Date:** 10-May-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

**This notice is NXP Company Proprietary.**



### Management Summary

Microcontroller products LPC5410xUK49 version "C" includes a die revision to fix errata issues and an upgraded bump process.

#### Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input checked="" type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

LPC5410xUK49 in WLCSP49 Package Change from Rev "B" to Rev "C"

### Description of Change

Microcontroller products LPC5410xUK49 in WLCSP49 package will change from version "B" to version "C". Changes included a die revision to fix errata issues and an upgraded bump process.

The following functional changes were made to product version "C":

- IRC frequency tolerance improvement over temperature to resolve errata IRC.1 as defined in the device errata sheet.
- System clock frequency improved to resolved errata Frequency.1 as defined in the device errata sheet.

The following bump process changes were made to product version "C":

- Under Bump Metal (UBM) and Re-Distribution Layer (RDL) change from a sputter to a plated process.
- Back side protection (BSP) material changes from 40um to 25um thickness.
- Overall maximum package thickness changes from 0.58mm to 0.565mm (see package drawing in attached datasheet).

A revised data sheet, LPC5410x v2.10 is available at <https://www.nxp.com/docs/en/data-sheet/LPC5410X.pdf>.

#### **Reason for Change**

- 1) To fix errata IRC.1 and Frequency.1.
- 2) The sputter UBM process is outdated and has been obsoleted by the assembly vendor. The assembly process is being upgraded to the current process already qualified by the LPC5411xUK49.

#### **Identification of Affected Products**

Top side marking

The change applies to product version "C" visible on the top side marking.

### **Product Availability**

#### **Sample Information**

Samples are available upon request

#### **Production**

Planned first shipment 10-May-2019

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

Product overall height is reduced by 15um due to change in back side protection thickness.

Product functionality changes to fix errata issues IRC.1 and Frequency.1.

#### **Data Sheet Revision**

A new datasheet will be issued

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Additional information**

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)

### **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 11-Mar-2019.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Tim Camenzind

**Position** Senior Quality Engineer

**e-mail address** [tim.camenzind@nxp.com](mailto:tim.camenzind@nxp.com)

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NXP Quality Management Team.

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